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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/684,874	10/15/2003	Hiroji Aga	109725.01	4805	
25944 75	590 06/17/2005		EXAMINER		
OLIFF & BERRIDGE, PLC P.O. BOX 19928			ESTRADA, MICHELLE		
ALEXANDRIA, VA 22320			ART UNIT	PAPER NUMBER	
			2823		
			DATE MAILED: 06/17/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)					
	10/684,874	AGA ET AL.					
Office Action Summary	Examiner	Art Unit					
•	Michelle Estrada	2823					
The MAILING DATE of this communication apperent of the Reply	The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).							
Status							
1) Responsive to communication(s) filed on 29 Se	eptember 2004.	•					
2a)☐ This action is FINAL . 2b)☒ This	action is non-final.						
3) Since this application is in condition for allowan							
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	3 O.G. 213.					
Disposition of Claims							
4) Claim(s) <u>1-3</u> is/are pending in the application.							
4a) Of the above claim(s) is/are withdraw	vn from consideration.						
5) Claim(s) is/are allowed.							
6)⊠ Claim(s) <u>1-3</u> is/are rejected.							
7) Claim(s) is/are objected to.	1						
8) Claim(s) are subject to restriction and/or	election requirement.						
Application Papers							
9) The specification is objected to by the Examiner							
10)☐ The drawing(s) filed on is/are: a)☐ acce							
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.							
The oath of declaration is objected to by the Ex-	ammer. Note the attached Office	Action of form F10-132.					
Priority under 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received.							
2. Certified copies of the priority documents have been received in Application No							
3. Copies of the certified copies of the priority documents have been received in this National Stage							
application from the International Bureau (PCT Rule 17.2(a)).							
* See the attached detailed Office action for a list of the certified copies not received.							
Attachment(s)							
1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413)							
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date Notice of Informal Patent Application (PTO-152)							
Paper No(s)/Mail Date <u>9/29/04</u> . 6) Other:							

DETAILED ACTION

Information Disclosure Statement

In the IDS filed 9/24/05, the US patent documents were already cited in the PTO-892 mailed 6/29/04.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1 and 2 are rejected under 35 U.S.C. 103(a) as being unpatentable over the combination of Yamamoto (JP-10275905), Murakami et al. (2004/0040491) and Wolf et al. (Vol. 1).

With respect to claim 1, Yamamoto discloses a method for producing an SOI wafer by the hydrogen ion delamination method comprising at least a step of bonding a base wafer (5) and a bond wafer (1) having a micro bubble layer formed by gas ion implantation (See fig. 1C) and a step of delaminating a wafer having an SOI layer at the micro bubble as a border (See fig. 1E).

Yamamoto does not disclose wherein a CZ wafer produced from a single crystal ingot of which COPs are reduced for the whole crystal is used as the bond wafer.

Wolf et al. (Vol. 1) discloses that the CZ wafer can be produced from a single crystal ingot (See pages 23-25).

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It would have been within the scope of one of ordinary skill in the art to combine the teachings of Yamamoto and Wolf et al. to enable production of the CZ wafer to be performed in the process of Yamamoto because it has a relative high degree of crystal purity and it helps to simplify the process.

Murakami et al. discloses a silicon single crystal ingot of which COPs are reduced for the whole crystal (Page 2, Paragraph [0022] and Page 3, Paragraph [0052]).

It would have been within the scope of one of ordinary skill in the art to combine the teachings of Yamamoto, Murakami et al. and Wolf et al. to enable the crystal ingot formation step of Yamamoto and Wolf et al. to be performed according to the teachings of Murakami et al. because one of ordinary skill in the art would have been motivated to look to alternative suitable methods of performing the disclosed crystal ingot formation step of Yamamoto and Wolf et al. and art recognized suitability for an intended purpose has been recognized to be motivation to combine. See MPEP 2144.07. Further, it will enhance quality of the product.

With respect to claim 2, Yamamoto discloses wherein the wafer having an SOI layer is subjected to a heat treatment under an atmosphere containing hydrogen in a batch processing type furnace after the delamination step (See Abstract).

With respect to claim 3, it is inherent that the process of Yamamoto will result in an SOI wafer which has a RMS value of 0.5 nm or less concerning surface roughness for both 1 μ m square and 10 μ m square, because the same process is being performed in Yamamoto as that of the instant invention and it will yield the same result.

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Response to Arguments

Applicant's arguments filed 9/29/04 have been fully considered but they are not persuasive.

In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., when an ordinary CZ wafer is used as a bond wafer to form an SOI wafer, the buried oxide layer is etched through COPs in the SOI layer when the delaminated SOI wafer is subjected to heat treatment in the atmosphere containing hydrogen or argon) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

Applicant argues that none of the references disclose that generation of pits can be prevented or reduced by using a CZ wafer produced from a single crystal ingot of which COPs are reduced for the whole crystal is used as the bond wafer to form an SOI wafer. However, it is not necessary for the reference to disclose that the process of the reference is performed to achieve the same goals as applicant or to obtain the same advantages recognized by applicant. It is sufficient that the process suggested by the reference alone or in combination with the remaining references is encompassed by the instant claims.

Applicant argues that none of the references teach the benefits that can be achieved by the method of claim 1. However, it is not necessary for the reference to disclose that the process of the reference is performed to achieve the same goals as

applicant or to obtain the same advantages recognized by applicant. It is sufficient that the process suggested by the reference alone or in combination with the remaining references is encompassed by the instant claims.

The remaining arguments are moot in view of the new grounds of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Michelle Estrada whose telephone number is 571-272-1858. The examiner can normally be reached on Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 571-272-2800.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should

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you have questions on access to the Private PAIR system, contact the Electronic

Business Center (EBC) at 866-217-9197 (toll-free).

George Fourson
Primary Examiner
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MEstrada June 1, 2005